

## HIGH-EFFICIENCY MODULE DESIGN

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### Principal Results

- FABRICATED MODULE WITH HIGH SUB-BANDGAP REFLECTIVITY AND EFFICIENCY OF 13.7%.
- FABRICATED LARGE-AREA CELLS WITH EFFICIENCY OVER 18%.

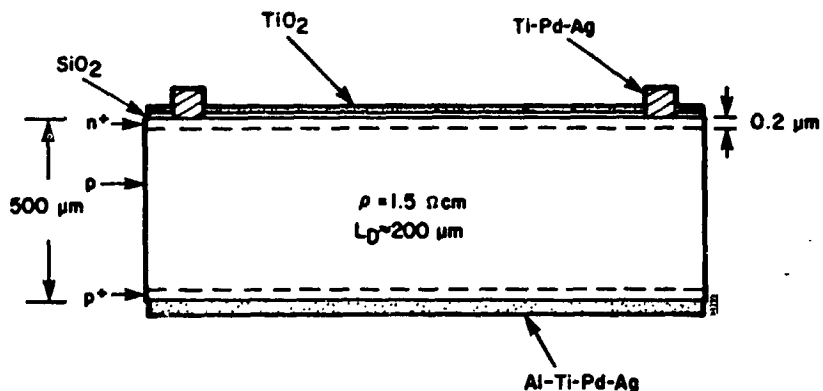
### Objectives

- FABRICATION OF MODULES WITH EMPHASIS ON REDUCED OPERATING TEMPERATURE.
- FABRICATION OF HIGHLY EFFICIENT MODULES.
- EVALUATION OF POSSIBLE TRADE-OFF BETWEEN HIGH EFFICIENCY AND LOW NOCT.

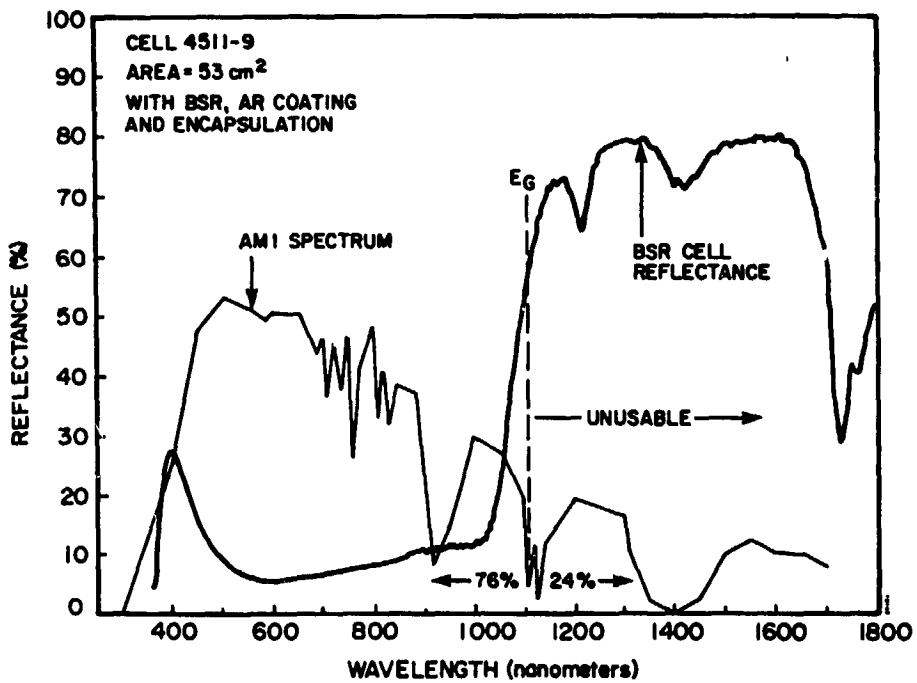
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Cell Design



- AI USED FOR BSR
- SiO<sub>2</sub> USED TO PASSIVATE SURFACE
- p<sup>+</sup> SIMPLE OHMIC CONTACT (NOT BSF)
- NO EDGE PASSIVATION USED



MODULE DEVELOPMENT AND ENGINEERING SCIENCES

Assembly Performance

(AM1.5, 100 mW/cm<sup>2</sup>, T= 25°C)  
Tested by JPL

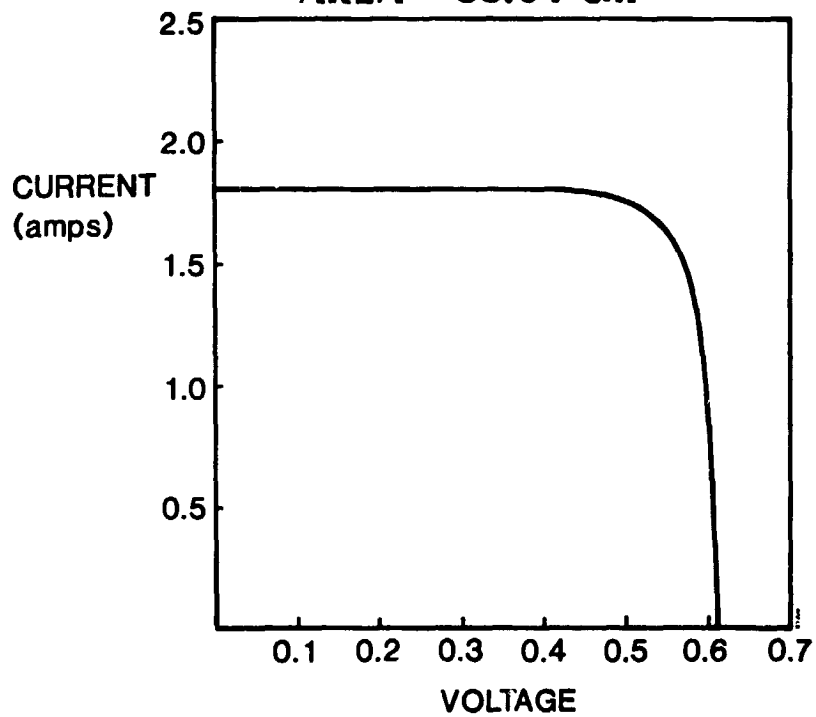
Eff = 17.1%

V<sub>oc</sub> = 611 mV

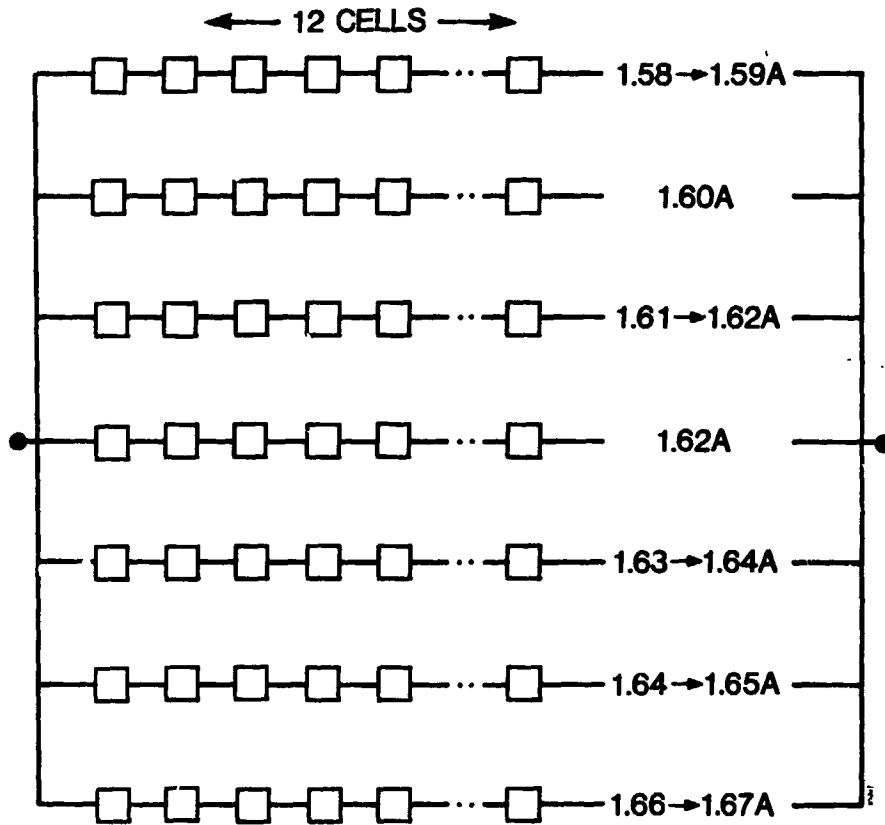
J<sub>sc</sub> = 34 mA/cm<sup>2</sup>

FF = 82.5%

AREA = 53.04 cm<sup>2</sup>



Module Circuit and Mismatch Loss



**$I_{mp}$  OF EACH CELL WITHIN  
1% OF THE STRING AVERAGE.**

**ALL STRINGS HAVE  $\Sigma V_{mp}$   
of  $6.053 \pm .001$  mV.**

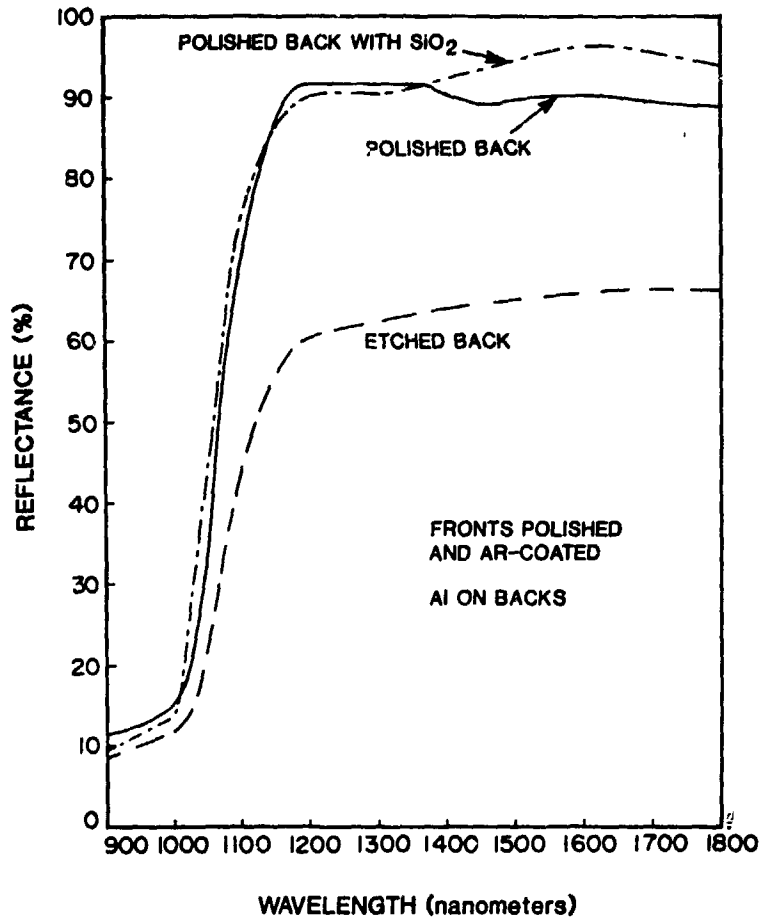
**AVE. Eff = 15.4%**

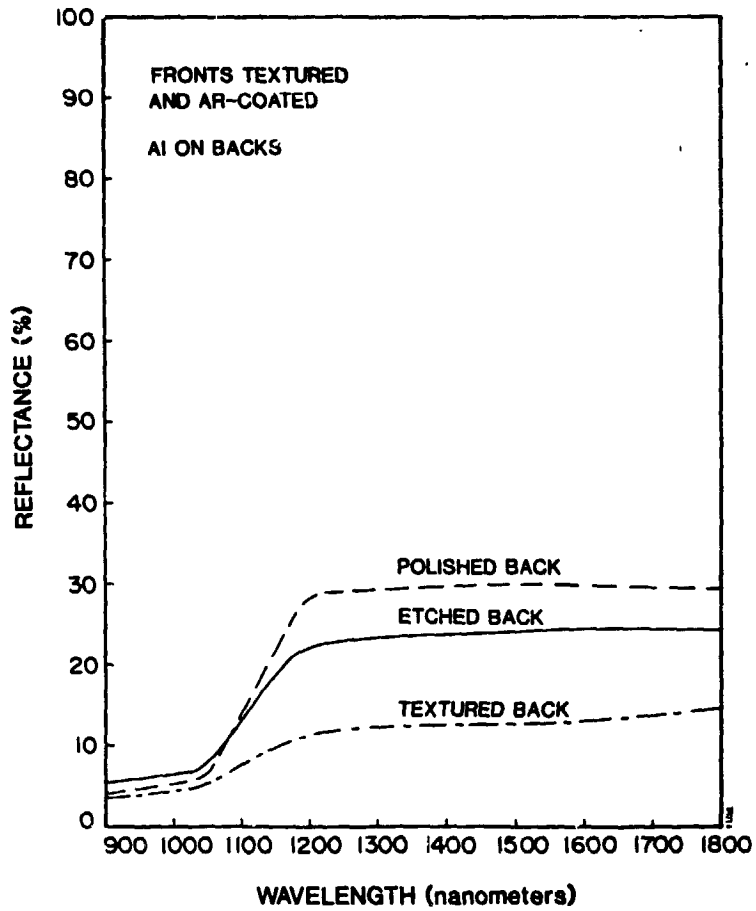


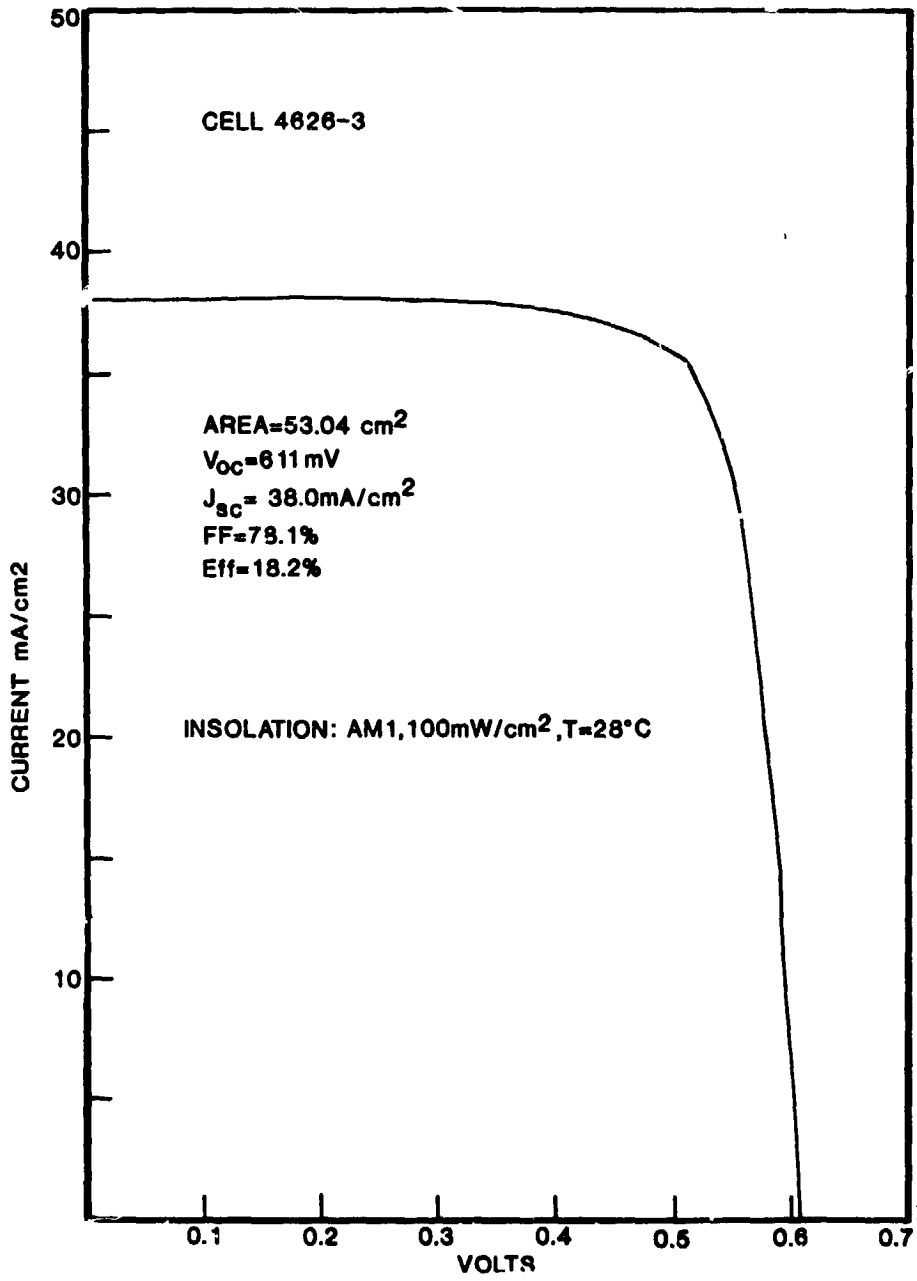
Options in Cell Design

- POLISHED VERSUS TEXTURE
  - POLISHED YIELDS BEST SUB-BANDGAP REFLECTION
  - TEXTURE YIELDS LOWER OVERALL REFLECTION
  
- LOW RESISTIVITY SILICON ( $\sim 0.3 \text{ } \Omega\text{-cm}$ )
  - HIGHER  $V_{oc}$  POSSIBLE
  - REQUIRES PRECISE DOPING
  
- REDUCE THICKNESS, ADD BACK PASSIVATION
  - YIELDS PROBLEMS?
  - REQUIRES PRECISE DOPING
  - OFFERS HIGHER EFFICIENCY

MODULE DEVELOPMENT AND ENGINEERING SCIENCES









MODULE DEVELOPMENT AND ENGINEERING SCIENCES

Furnace-Annealed Texture-Etched Large-Area Cells

$V_{oc}$ (V)	$I_{sc}$ (A)	$J_{sc}$ mA/cm <sup>2</sup>	FF (%)	Eff (%)
0.610	2.001	37.7	77.5	17.8
0.611	2.018	38.6	78.1	18.2
0.606	1.985	37.4	77.5	17.6
0.602	1.933	36.5	78.1	17.1
0.610	2.016	38.0	78.4	18.2
0.604	1.965	37.1	77.7	17.4
0.610	2.011	37.9	77.7	18.0
0.609	2.028	38.2	77.5	18.1
0.609	2.014	38.0	76.5	17.7
0.609	2.013	38.0	77.9	18.0
0.611	2.026	38.2	77.8	18.2
0.606	1.964	37.0	77.8	17.5
0.608	1.985	37.4	76.9	17.5
0.607	2.018	38.0	76.2	17.6
0.611	2.033	38.3	77.4	18.1
0.607	1.980	37.3	77.4	17.5
0.609	2.022	38.1	77.5	18.0
0.609	2.011	37.9	78.3	18.1
0.610	2.029	38.2	77.0	18.0
0.607	1.984	37.4	77.5	17.6
0.601	1.930	36.4	76.6	16.7
0.603	1.959	36.9	76.2	17.0
0.608	1.997	37.6	77.4	17.7
0.003	0.031	0.6	0.6	0.4

NOTES: AREA=53cm<sup>2</sup>. T=28 °C. INSULATION WAS SIMULATED AM1, 1J0mW/cm<sup>2</sup>.

Projections for Module Made of Texture-Etched Cells

	POLISHED CELLS (ACTUAL)	TEXTURED CELLS (PROJECTED)
AVERAGE CELL EFFICIENCY	15.4%	17.7%
PACKING FACTOR (90%)	13.9%	15.9%
INTERCONNECT LOSSES (1.4%)	13.7%	15.7%

Conclusions

- BSR CELLS OFFER HIGH REFLECTION OF SUB-BANDGAP PHOTONS.
- ENCAPSULATED CELL EFFICIENCY OF 17.1% HAS BEEN ACHIEVED, WITH A 53cm<sup>2</sup> CELL (MEASURED AT JPL).
- MODULE EFFICIENCY OF 13.7% HAS BEEN ACHIEVED, NOCT IS 45°C (MEASURED AT JPL).
- TEXTURED CELL EFFICIENCY OF 18.2% HAS BEEN ACHIEVED WITH A 53cm<sup>2</sup> CELL.
- MODULE EFFICIENCY GREATER THAN 15% IS REALISTIC IN THE VERY NEAR FUTURE.